



## Advanced Digital Non-Destructive Testing Technology

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### Message from the Guest Editors

Dear Colleagues,

Non-destructive testing techniques using advanced sensors and signal-processing methods play an important role in industrial applied science. Due to the difference in their physical mechanisms and testing principles, the magnetic flux leakage, the eddy current, acoustic emissions, and guide ultrasonic wave testing, as well as other inspection methods for industrial objects, are widely used in various scenes.

This Special Issue invites authors to submit high-quality research articles that cover but are not limited to different topics of advanced digital non-destructive testing; smart sensing; advanced sensors; the Industrial Internet of Things (IoT) for inspection; advanced electromagnetic models and theories; the innovative design of the detector; digital imaging and signal processing; magnetic model optimization; multi-sensor data fusion; applications of AI in defect detection; materials characterization; digital and cognitive twins for monitoring; innovative industrial applications; etc. This call for papers also welcomes contributions that explore other methodologies and practices of digital non-destructive testing theories and technologies.





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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